

**IN THE SPECIFICATION****IN THE ABSTRACT**

A method of making a microelectronic assembly includes providing a dielectric layer including a first major face ~~comprising~~ having a first adhesive, a second major face ~~comprising~~ having a second adhesive, and a protective liner over the second adhesive, juxtaposing a plurality of microelectronic elements with the first major face of dielectric layer, and assembling the microelectronic elements with the dielectric layer by abutting the microelectronic elements against the first adhesive of the dielectric layer. The method also includes at least partially severing the dielectric layer while maintaining the protective liner as a single piece of material so as to form a plurality of individual microelectronic units overlying the protective liner, whereby each of the individual microelectronic units includes at least one of the microelectronic elements attached to an at least partially severed portion of the dielectric layer.

**[0043]** One preferred embodiment of the present invention is shown in FIGS. 1-8. Referring to FIGS. 1 and 2, a semiconductor wafer 10 includes a plurality of microelectronic elements 12 connected together. The wafer 10 has a bottom surface 11 and a top surface 13 and a two-dimensional array of microelectronic elements 12 defined by a number of rows 14 and columns 16. The rows 14 and columns 16 are defined by lines 17. In other preferred embodiments, the wafer 10 may comprise a plurality of microelectronic elements 12 arranged in a one-dimensional array. In other preferred embodiments, an assembly may comprise more than one microelectronic element, such as a pair of microelectronic elements, arranged in a side-by-side arrangement, in a plane, or a stacked arrangement, or a plurality of smaller assemblies of microelectronic elements,

Application No.: 10/614,069

Docket No.: TESSERA 3.0-298

such as a plurality of stacked semiconductor chips connected to one another.